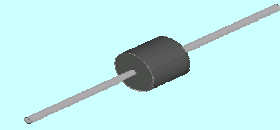


## MATERIAL COMPOSITION DECLARATION

Supplier: Fagor Electrónica S. Coop

Package: P-6



Part Number:

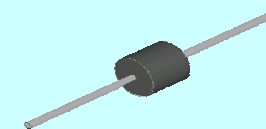
Description: General Purpose, Fast, Ultrafast

COMPOSITION PART	MATERIAL NAME	MATERIAL MASS( mg)	MATERIAL MASS( %)	ELEMENT NAME COMPOSITION	CAS Nº	ELEMENT % ( BY WEIGHT)	Cd (ppm)	Pb (ppm)	Hg (ppm)	Cr 6+ (ppm)	PBBs (ppm)	PBDEs (ppm)
LEAD FRAME	O2 Free Cu Wire	1,034.280	52.55%	Cu Oxygen	7440-50-8 7782-44-7	99,9 min 0,0015 max	< 2	< 2	< 2	< 2	< 5	< 5
ENCAPSULATION	Epoxy Moulding Compound	902.867	45.87%	SiO2 (Fused Silica)	60676-86-0	70-75	< 2	< 2	< 2	< 2	< 5	< 5
				Polyglycidyl Ether O-Cresol Formaldehyde	29690-82-2	10-15						
				Novolac	9003-35-4	5-10						
				Phenolic Resin	1309-64-4	1-3						
				Sb2O3	40039-93-8	1-3						
CHIP	Doped Silicon Glass Passivated	6.313	0.32%	Si	7440-21-3	90,6-92,1	< 2	43844 (**)	< 2	< 2	< 5	< 5
				Ni	7440-02-0	0,9-1,3						
				SiO2	7631-86-9	3,6-3,8						
				PbO2	1309-60-0	3,4-3,5						
				Al2O3	1344-28-1	0,3-0,5						
SOLDER PASTE	Pb/Sn5 Solder Paste	10.909	0.55%	Pb	7439-92-1	92,8 - 95,0	< 2	925013 (*)	< 2	< 2	< 5	< 5
				Sn	7440-31-5	4,5 - 5,5						
				Sb	7440-36-0	0.2						
COATING	Sn (100%)	13.631	0.69%	Sn Pb Cu Sb	7440-31-5 7439-92-1 7440-50-8 7440-36-0	99.85 0,05 max 0,05 max 0,05 max	< 2	< 2	< 2	< 2	< 5	< 5

## MATERIAL COMPOSITION DECLARATION

Supplier: Fagor Electrónica S. Coop

Package: P-6



Part Number:

Description: General Purpose, Fast, Ultrafast

COMPOSITION PART	MATERIAL NAME	MATERIAL MASS( mg)	MATERIAL MASS( %)	ELEMENT NAME COMPOSITION	CAS N°	ELEMENT % ( BY WEIGHT)	Cd (ppm)	Pb (ppm)	Hg (ppm)	Cr 6+ (ppm)	PBBs (ppm)	PBDEs (ppm)
PRINTING INK	Pigments in Acrylate	0.200	0.01%	2- Propenic, polimer with 2-ethyl-2-(Hydroxymethyl)-1,3=propanediol and 3a,4,7,7a-tetrahydro-1,3-isobenzofurandione	53192-18-0	65-70	< 2	< 2	< 2	< 2	< 5	< 5
				Aluminum	7429-90-5	15-20						
				Silica	112945-52-5	1-5						
				Methanone,(1-hydroxycyclohexyl) Phenyl	947-19-3	1-5						
				Benzoic,acid,4-(dimethylamino)-2-ethylhexyl ester	21245-01-2	5-10						
WHOLE ITEM		1,968.200	100.00%									

**Exception according to annex of Directive 2002/95/EC (RoHS):**

- \* Lead in high melting temperature type solders (i.e. tin-lead solder alloys containing more than 85% lead)
- \*\* Lead in glass of cathode ray tubes, electronic componentes and fluorescent tubes

